

- 1. Substrate to minimum of 1:80 achieved falls and primed as required for VCL
- 2. SIG D&T Vapour Control Layer
- 3. SIG D&T Approved Insulation bonded with IKOPro high performance PU adhesive. Boards to be primed with AH+ WP Primer and all joints to be sealed with AH+

DRAWING No:

AH+4warm

REVISION: